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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	16MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2120ckfp-u0

1.4 Product Information

Table 1.3 lists Product Information for R8C/20 Group and Table 1.4 lists Product Information for R8C/21 Group.

Table 1.3 Product Information for R8C/20 Group

Current of Aug. 2008

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks	
R5F21206JFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	J version	Flash memory version
R5F21207JFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21208JFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2120AJFP	96 Kbytes	5 Kbytes	PLQP0048KB-A		
R5F2120CJFP	128 Kbytes ⁽¹⁾	6 Kbytes	PLQP0048KB-A		
R5F21206KFP	32 Kbytes	2 Kbytes	PLQP0048KB-A	K version	
R5F21207KFP	48 Kbytes	2.5 Kbytes	PLQP0048KB-A		
R5F21208KFP	64 Kbytes	3 Kbytes	PLQP0048KB-A		
R5F2120AKFP	96 Kbytes	5 Kbytes	PLQP0048KB-A		
R5F2120CKFP	128 Kbytes ⁽¹⁾	6 Kbytes	PLQP0048KB-A		

NOTE:

- Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **23. Notes on Emulator Debugger** of Hardware Manual.

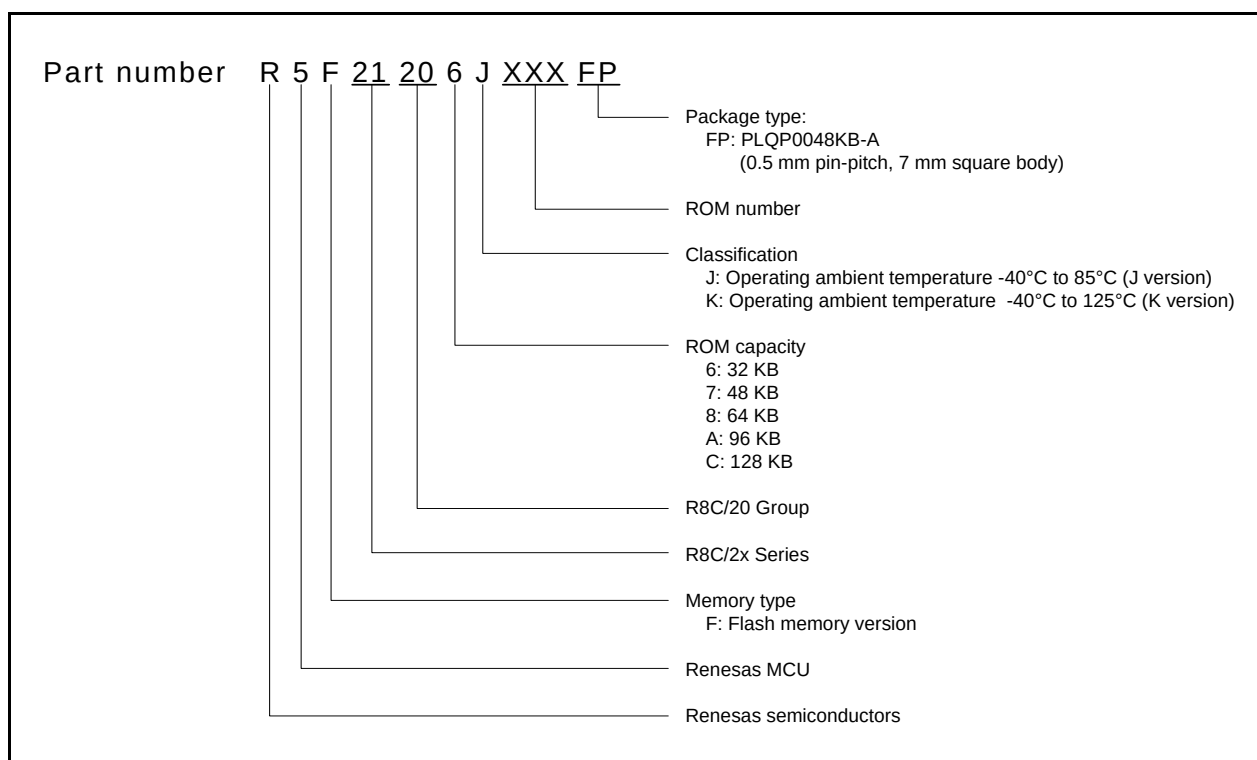


Figure 1.2 Type Number, Memory Size, and Package of R8C/20 Group

1.5 Pin Assignments

Figure 1.4 shows Pin Assignments (Top View).

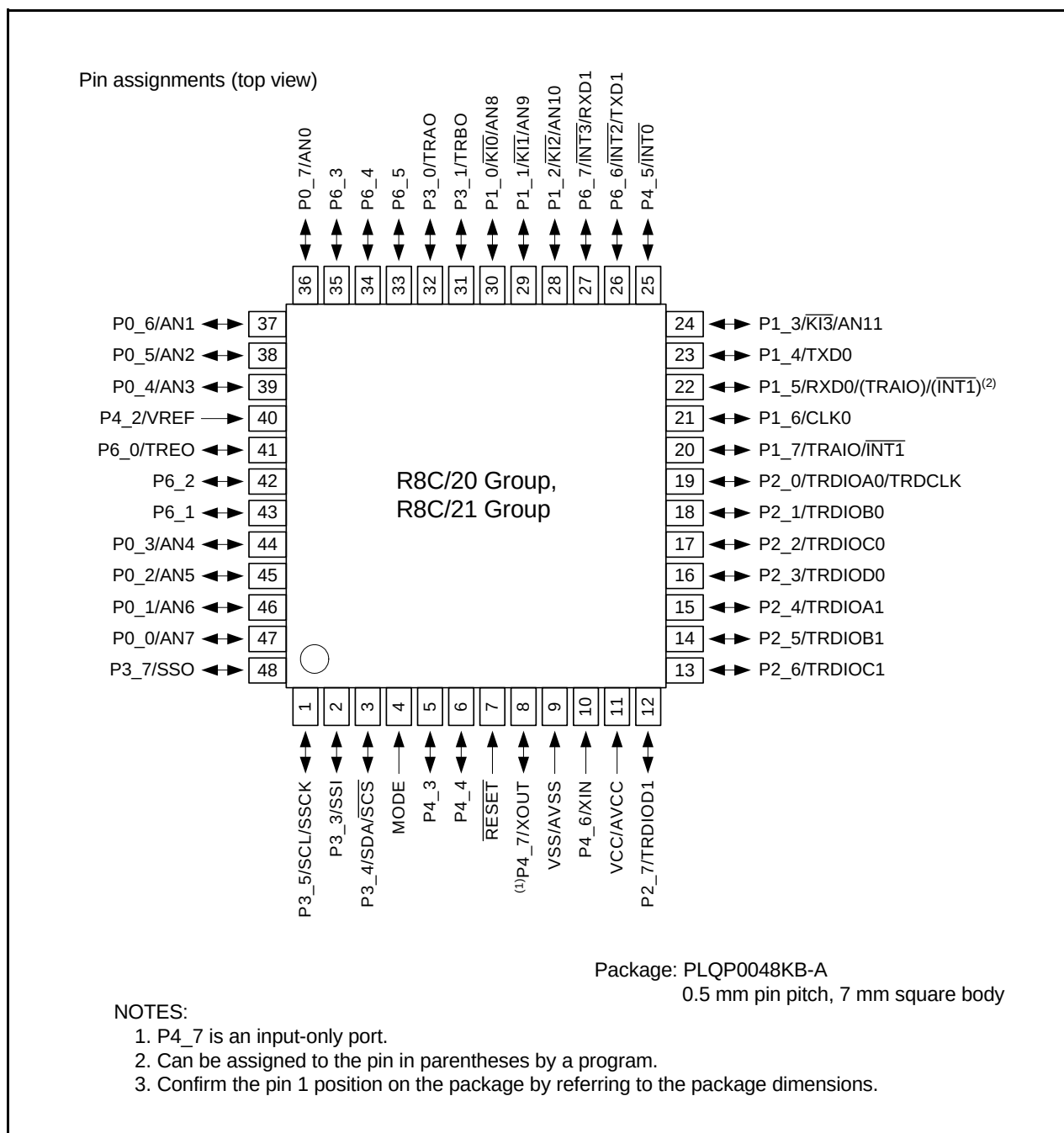


Figure 1.4 Pin Assignments (Top View)

1.6 Pin Functions

Table 1.5 lists the Pin Functions and Table 1.6 lists the Pin Name Information by Pin Number.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power Supply Input	VCC VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog Power Supply Input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset Input	RESET	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN Clock Input	XIN	I	These pins are provided for the XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
XIN Clock Output	XOUT	O	
INT Interrupt Input	INT0 to INT3	I	INT interrupt input pins. INT0 Timer RD input pins. INT1 Timer RA input pins.
Key Input Interrupt	KI0 to KI3	I	Key input interrupt input pins.
Timer RA	TRAIO	I/O	Timer RA I/O pin.
	TRA0	O	Timer RA output pin.
Timer RB	TRBO	O	Timer RB output pin.
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDI0C0, TRDI0C1, TRDI0D0, TRDI0D1	I/O	Timer RD I/O ports.
	TRDCLK	I	External clock input pin.
Timer RE	TRE0	O	Divided clock output pin.
Serial Interface	CLK0	I/O	Transfer clock I/O pin.
	RXD0, RXD1	I	Serial data input pins.
	TXD0, TXD1	O	Serial data output pins.
I ² C Bus Interface	SCL	I/O	Clock I/O pin.
	SDA	I/O	Data I/O pin.
Clock Synchronous Serial I/O with Chip Select	SSI	I/O	Data I/O pin.
	SCS	I/O	Chip-select signal I/O pin.
	SSCK	I/O	Clock I/O pin.
	SSO	I/O	Data I/O pin.
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter.
A/D Converter	AN0 to AN11	I	Analog input pins to A/D converter.
I/O Port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6_0 to P6_7	I/O	CMOS I/O ports. Each port contains an input/output select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by a program.
Input Port	P4_2, P4_6, P4_7	I	Input only ports.

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. Of these, R0, R1, R2, R3, A0, A1, and FB comprise a register bank. Two sets of register banks are provided.

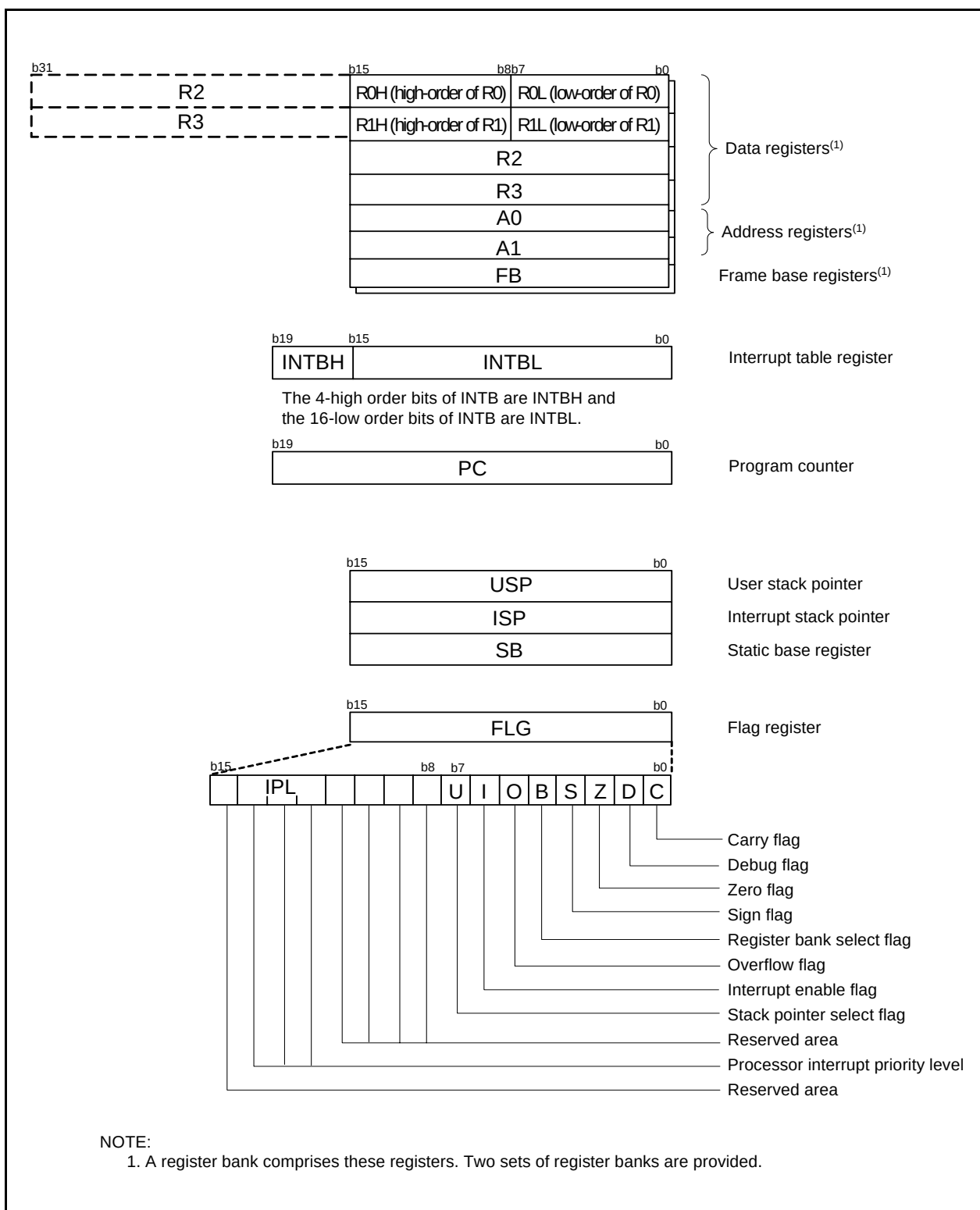


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3.

R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies R3R1 as R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0.

A1 can be combined with A0 to be used a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB, a 20-bit register, indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each.

The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU status.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debug only. Set to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation resulted in 0; otherwise, 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation resulted in a negative value; otherwise, 0.

2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is 0. The register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when the operation resulted in an overflow; otherwise, 0.

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h			
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register/IIC Bus Interrupt Control Register ⁽²⁾	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.3 SFR Information (3)⁽¹⁾

Address	Register	Symbol	After reset
0080h			
0081h			
0082h			
0083h			
0084h			
0085h			
0086h			
0087h			
0088h			
0089h			
008Ah			
008Bh			
008Ch			
008Dh			
008Eh			
008Fh			
0090h			
0091h			
0092h			
0093h			
0094h			
0095h			
0096h			
0097h			
0098h			
0099h			
009Ah			
009Bh			
009Ch			
009Dh			
009Eh			
009Fh			
00A0h	UART0 Transmit/Receive Mode Register	U0MR	00h
00A1h	UART0 Bit Rate Register	U0BRG	XXh
00A2h	UART0 Transmit Buffer Register	U0TB	XXh
00A3h			XXh
00A4h	UART0 Transmit/Receive Control Register 0	U0C0	00001000b
00A5h	UART0 Transmit/Receive Control Register 1	U0C1	00000010b
00A6h	UART0 Receive Buffer Register	U0RB	XXh
00A7h			XXh
00A8h	UART1 Transmit/Receive Mode Register	U1MR	00h
00A9h	UART1 Bit Rate Register	U1BRG	XXh
00AAh	UART1 Transmit Buffer Register	U1TB	XXh
00ABh			XXh
00ACh	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
00ADh	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
00AEh	UART1 Receive Buffer Register	U1RB	XXh
00AFh			XXh
00B0h			
00B1h			
00B2h			
00B3h			
00B4h			
00B5h			
00B6h			
00B7h			
00B8h	SS Control Register H/IIC Bus Control Register 1 ⁽²⁾	SSCRH/ICCR1	00h
00B9h	SS Control Register L/IIC Bus Control Register 2 ⁽²⁾	SSCRL/ICCR2	01111101b
00BAh	SS Mode Register/IIC Bus Mode Register 1 ⁽²⁾	SSMR/ICMR	00011000b
00BBh	SS Enable Register/IIC Bus Interrupt Enable Register ⁽²⁾	SSER/ICIER	00h
00BCh	SS Status Register/IIC Bus Status Register ⁽²⁾	SSSR/ICSR	00h/0000X000b
00BDh	SS Mode Register 2/Slave Address Register ⁽²⁾	SSMR2/SAR	00h
00BEh	SS Transmit Data Register/IIC Bus Transmit Data Register ⁽²⁾	SSTDR/ICDRT	FFh
00BFh	SS Receive Data Register/IIC Bus Receive Data Register ⁽²⁾	SSRDR/ICDRR	FFh

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 5.4 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/20 Group	100 ⁽³⁾	–	–	times
		R8C/21 Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until erase suspend		–	–	97 + CPU clock × 6 cycle	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3 + CPU clock × 4 cycle	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times.
For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure endurance can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.8 Power-on Reset Circuit, Voltage Monitor 1 Reset Circuit Electrical Characteristics⁽³⁾

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{por1}	Power-on reset valid voltage ⁽⁴⁾		–	–	0.1	V
V _{por2}	Power-on reset or voltage monitor 1 valid voltage		0	–	V _{det1}	V
tr _{th}	External power V _{CC} rise gradient	V _{CC} ≤ 3.6 V	20 ⁽²⁾	–	–	mV/msec
		V _{CC} > 3.6 V	20 ⁽²⁾	–	2,000	mV/msec

NOTES:

1. T_{opr} = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.
2. This condition (the minimum value of external power V_{CC} rise gradient) does not apply if V_{por2} ≥ 1.0 V.
3. To use the power-on reset function, enable voltage monitor 1 reset by setting the LVD1ON bit in the OFS register to 0, the VW1C0 and VW1C6 bits in the VW1C register to 1 respectively, and the VCA26 bit in the VCA2 register to 1.
4. t_{w(por1)} indicates the duration the external power V_{CC} must be held below the effective voltage (V_{por1}) to enable a power on reset. When turning on the power for the first time, maintain t_{w(por1)} for 30s or more if -20°C ≤ T_{opr} ≤ 125°C, maintain t_{w(por1)} for 3,000s or more if -40°C ≤ T_{opr} < -20°C.

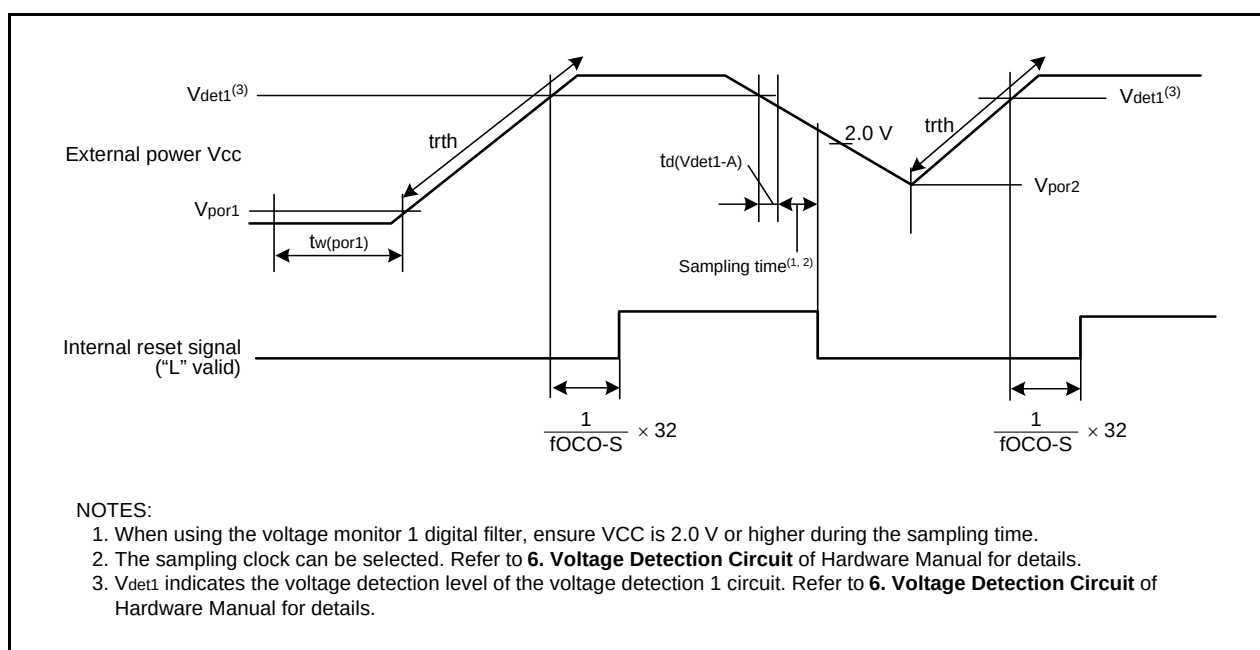
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.9 High-Speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO40M	High-speed on-chip oscillator frequency temperature • supply voltage dependence	V _{CC} = 4.75 V to 5.25 V, 0°C ≤ Topr ≤ 60°C ⁽²⁾	39.2	40	40.8	MHz
		V _{CC} = 3.0 V to 5.25 V, -20°C ≤ Topr ≤ 85°C ⁽²⁾	38.8	40	41.2	MHz
		V _{CC} = 3.0 V to 5.5 V, -40°C ≤ Topr ≤ 85°C ⁽²⁾	38.4	40	41.6	MHz
		V _{CC} = 3.0 V to 5.5 V, -40°C ≤ Topr ≤ 125°C ⁽²⁾	38.0	40	42.0	MHz
		V _{CC} = 2.7 V to 5.5 V, -40°C ≤ Topr ≤ 125°C ⁽²⁾	37.6	40	42.4	MHz
–	The value of the FRA1 register when the reset is deasserted		08h	40	F7h	–
–	High-speed on-chip oscillator adjustment range	Adjust the FRA1 register to -1 bit (the value when the reset is deasserted)	–	+ 0.3	–	MHz
–	Oscillation stability time		–	10	100	μs
–	Self power consumption when high-speed on-chip oscillator oscillating	V _{CC} = 5.0 V, Topr = 25°C	–	600	–	μA

NOTES:

1. V_{CC} = 2.7 V to 5.5 V, Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.
2. The standard value shows when the reset is deasserted for the FRA1 register.

Table 5.10 Low-Speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		40	125	250	kHz
–	Oscillation stability time		–	10	100	μs
–	Self power consumption when low-speed on-chip oscillator oscillating	V _{CC} = 5.0 V, Topr = 25°C	–	15	–	μA

NOTE:

1. V_{CC} = 2.7 V to 5.5 V, Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.

Table 5.11 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		1	–	2000	μs
t _d (R-S)	STOP exit time ⁽³⁾		–	–	150	μs

NOTES:

1. The measurement condition is V_{CC} = 2.7 to 5.5 V and Topr = -40°C to 85°C (J version) / -40°C to 125°C (K version), unless otherwise specified.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts since the interrupt is acknowledged to exit stop mode.

Table 5.12 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc ⁽²⁾
t _{HI}	SSCK clock "H" width			0.4	–	0.6	tsucyc
t _{LO}	SSCK clock "L" width			0.4	–	0.6	tsucyc
trise	SSCK clock rising time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tfall	SSCK clock falling time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
t _H	SSO, SSI data input hold time			1	–	–	tcyc ⁽²⁾
t _{LEAD}	SCS setup time	Slave		1tcyc + 50	–	–	ns
t _{LAG}	SCS hold time	Slave		1tcyc + 50	–	–	ns
t _{OD}	SSO, SSI data output delay time			–	–	1	tcyc ⁽²⁾
t _{SA}	SSI slave access time			–	–	1tcyc + 100	ns
t _{OR}	SSI slave out open time			–	–	1tcyc + 100	ns

NOTES:

1. V_{CC} = 2.7 to 5.5 V, V_{SS} = 0 V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
2. 1tcyc = 1/f₁(s)

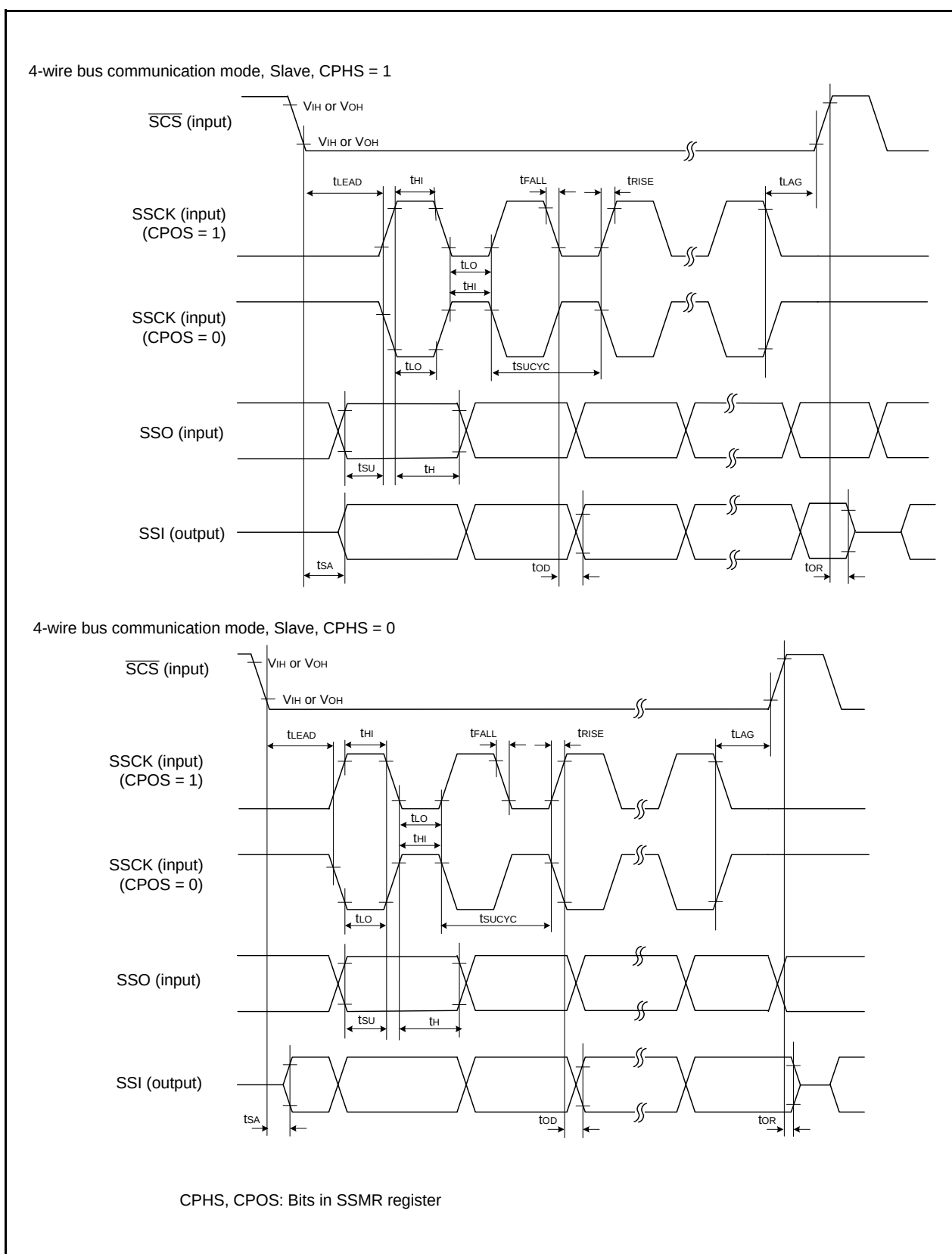


Figure 5.5 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

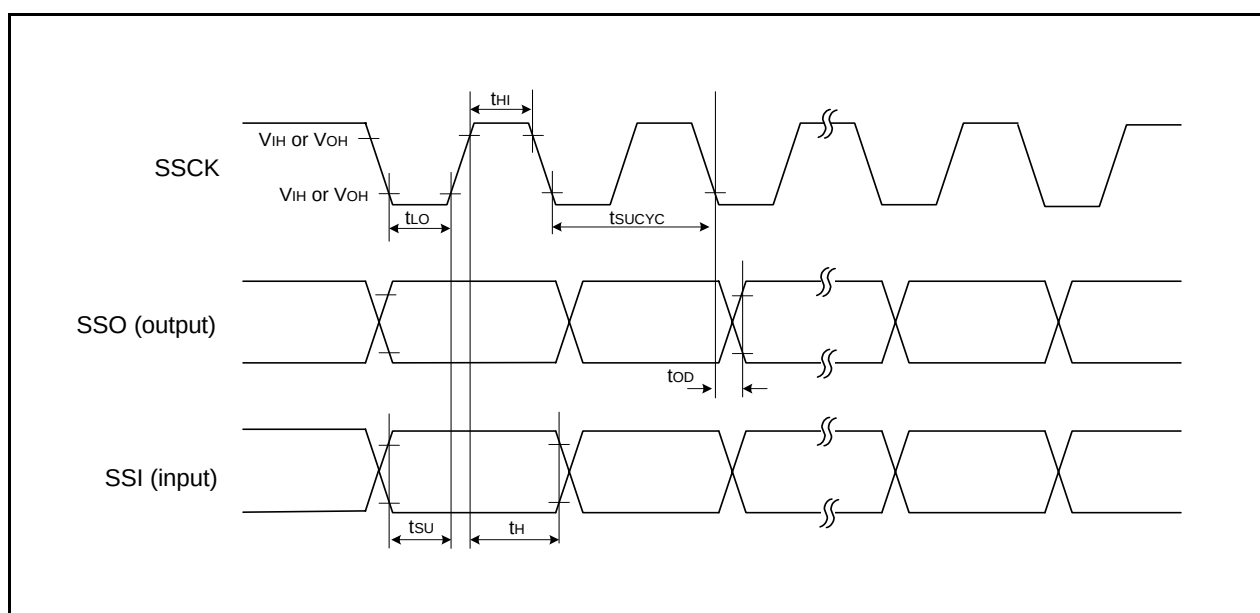


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.13 Timing Requirements of I²C Bus Interface⁽¹⁾

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12t _{CYC} + 600 ⁽²⁾	—	—	ns
t _{SCLH}	SCL input "H" width		3t _{CYC} + 300 ⁽²⁾	—	—	ns
t _{SCLL}	SCL input "L" width		5t _{CYC} + 300 ⁽²⁾	—	—	ns
t _{sf}	SCL, SDA input falling time		—	—	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		—	—	1t _{CYC} ⁽²⁾	ns
t _{BUF}	SDA input bus-free time		5t _{CYC} ⁽²⁾	—	—	ns
t _{STAH}	Start condition input hold time		3t _{CYC} ⁽²⁾	—	—	ns
t _{STAS}	Retransmit start condition input setup time		3t _{CYC} ⁽²⁾	—	—	ns
t _{STOP}	Stop condition input setup time		3t _{CYC} ⁽²⁾	—	—	ns
t _{SOAS}	Data input setup time		1t _{CYC} + 20 ⁽²⁾	—	—	ns
t _{SDAH}	Data input hold time		0	—	—	ns

NOTES:

1. V_{CC} = 2.7 to 5.5 V, V_{SS} = 0V at Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
2. 1t_{CYC} = 1/f₁(s)

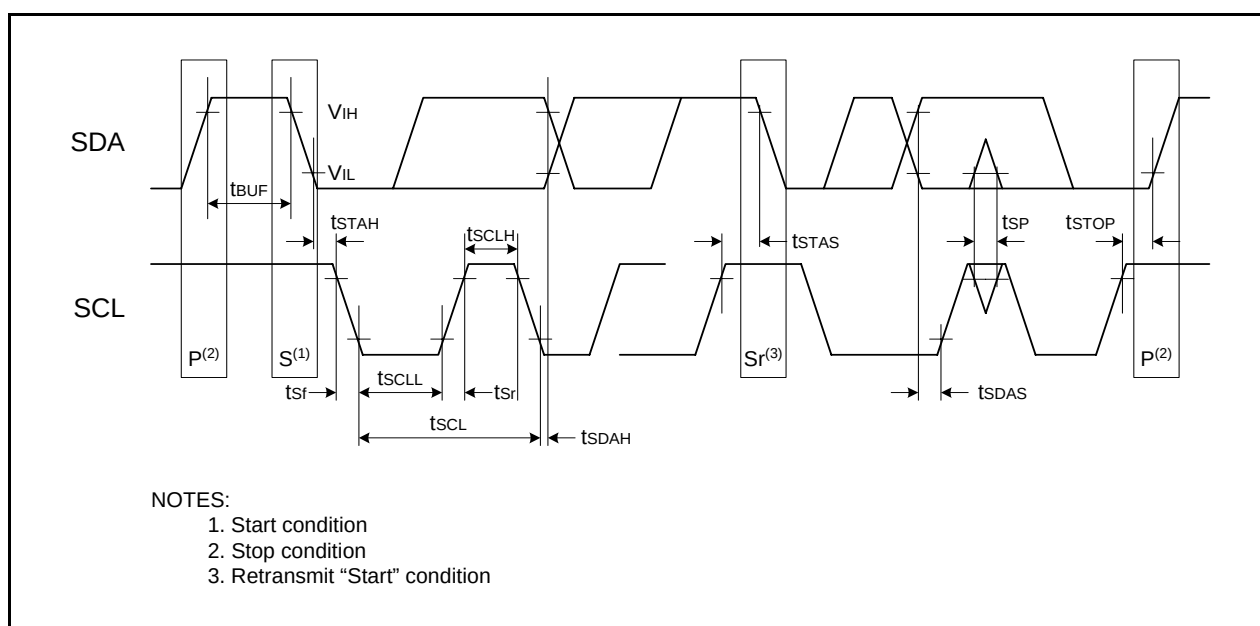
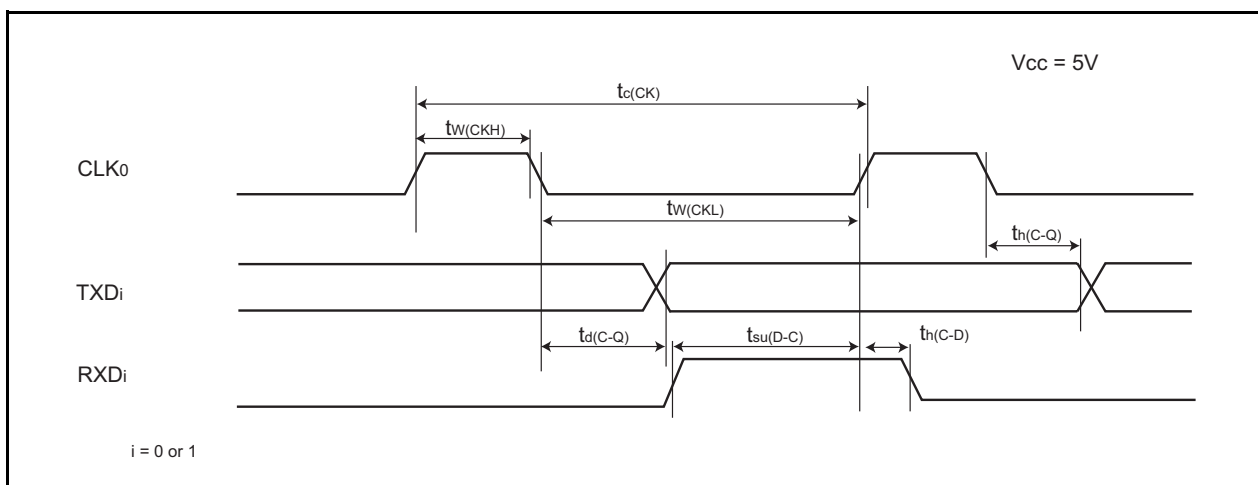
**Figure 5.7 I/O Timing of I²C Bus Interface**

Table 5.18 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	200	—	ns
$t_{w(CKH)}$	CLK0 input "H" width	100	—	ns
$t_{w(CKL)}$	CLK0 input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXD _i input setup time	50	—	ns
$t_{h(C-D)}$	RXD _i input hold time	90	—	ns

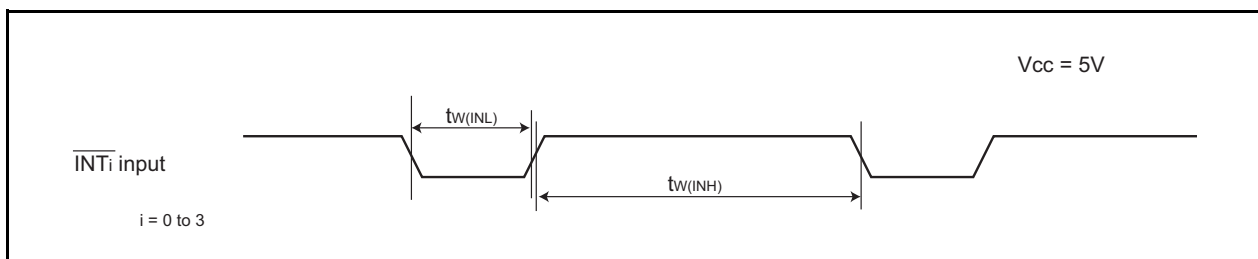
i = 0 or 1

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.19 External Interrupt $\overline{INT_i}$ (i = 0 to 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT_i}$ input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT_i}$ input "L" width	250 ⁽²⁾	—	ns

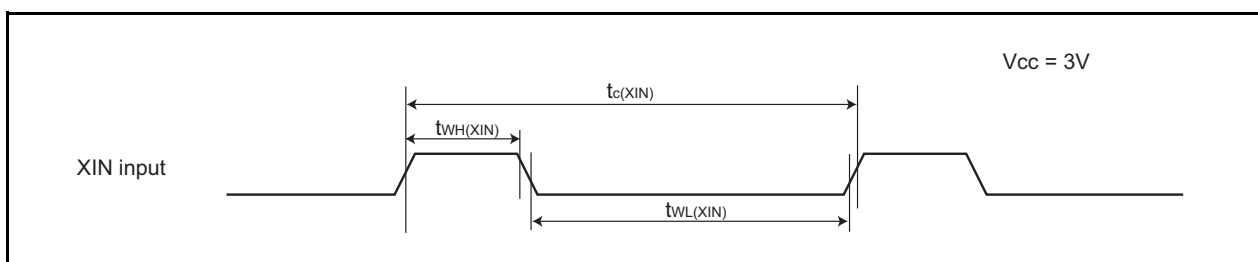
NOTES:

1. When selecting the digital filter by the $\overline{INT_i}$ input filter select bit, use the $\overline{INT_i}$ input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INT_i}$ input filter select bit, use the $\overline{INT_i}$ input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

**Figure 5.11 External Interrupt $\overline{INT_i}$ Input Timing Diagram when Vcc = 5 V (i = 0 to 3)**

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]**Table 5.22 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input "H" width	40	–	ns
$t_{WL(XIN)}$	XIN input "L" width	40	–	ns

**Figure 5.12 XIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.23 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input Cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	120	–	ns

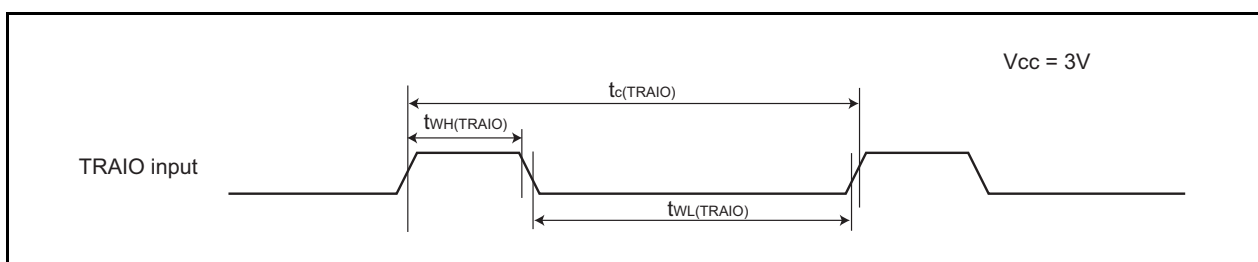
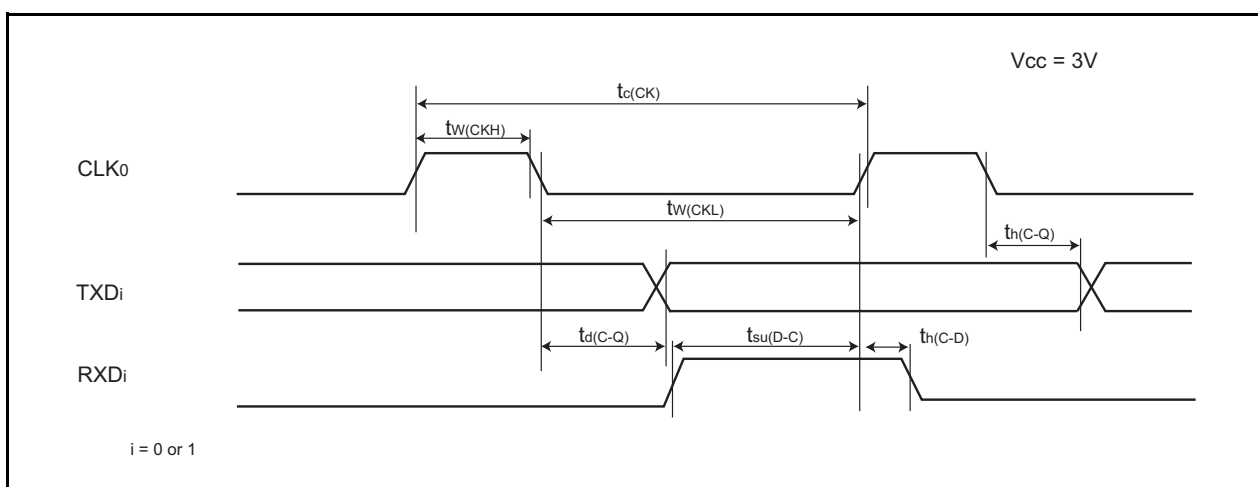
**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.24 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	300	—	ns
$t_{w(CKH)}$	CLK0 input "H" width	150	—	ns
$t_{w(CKL)}$	CLK0 input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

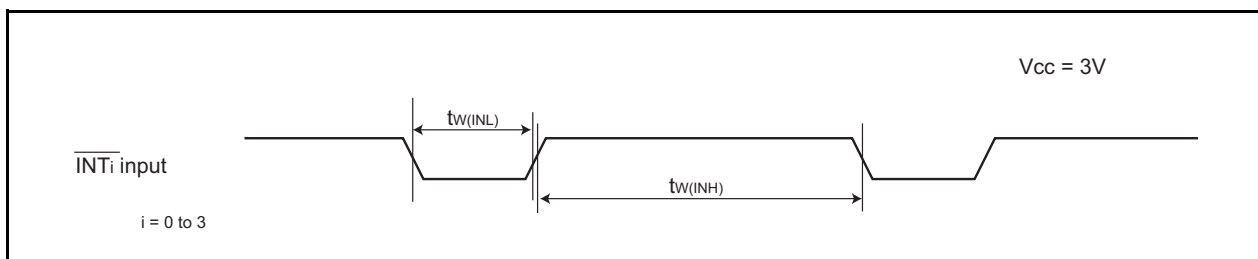
i = 0 or 1

**Figure 5.14 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.25 External Interrupt $\overline{INTi}$ (i = 0 to 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INTi}$ input "L" width	380 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use the $\overline{INTi}$ input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

**Figure 5.15 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 3 V (i = 0 to 3)**

REVISION HISTORY	R8C/20 Group, R8C/21 Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.10	Mar 08, 2005	–	First Edition issued
0.20	Sep 29, 2005	–	Words standardized - Clock synchronous serial interface → Clock synchronous serial I/O - Chip-select clock synchronous interface(SSU) → Clock synchronous serial I/O with chip select - I ² C bus interface(IIC) → I ² C bus interface
		2, 3	Table1.1 R8C/20 Group Performance, Table1.2 R8C/21 Group Performance Serial Interface revised: - Clock Synchronous Serial Interface: 1 channel I ² C bus Interface (3), Clock synchronous serial I/O with chip select - Power-On Reset Circuit added - Power Consumption value determined
		5, 6	Table 1.3 Product Information of R8C/20 Group, Table 1.4 Product Information of R8C/21 Group Date revised.
		7	Figure 1.4 Pin Assignment Pin name revised: - P3_5/SSCK(/SCL) → P3_5/ SCL/SSCK - P3_4/SCS(/SDA) → P3_4/ SDA /SCS - VSS → VSS/AVSS - VCC → VCC/AVCC - P1_5/RXD0/(TRAIO/INT1) → P1_5/RXD0/(TRAIO)/(INT1) - P6_6/INT2/(TXD1) → P6_6/INT2/TXD1 - P6_7/INT3/(RXD1) → P6_7/INT3/RXD1 - NOTE2 added
		8	Table 1.5 Pin Description - Analog Power Supply Input: line added - I ² C Bus Interface (IIC) → I ² C Bus Interface - SSU → Clock Synchronous Serial I/O with Chip Select
		9	Table 1.6 Pin Name Information by Pin Number revised - Pin Number 1: (SCL) → SCL - Pin Number 2: (SDA) → SDA - Pin Number 9: VSS → VSS/AVSS - Pin Number 11: VCC → VCC/AVCC - Pin Number 26: (TXD1) → TXD1 - Pin Number 27: (RXD1) → RXD1
		15	Table 4.1 SFR Information (1) revised - 0013h: XXXXX00b → 00h
		17	Table 4.3 SFR Information (3) revised - 00BCh: 0000X000b → 00h/0000X000b
		18	Table 4.4 SFR Information (4) revised - 00D6h: 00000XXXb → 00h - 00F5h: UART1 Function Select Register added
		19	Table 4.5 SFR Information (5) revised - 0104h: TRATR → TRA

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Rev.	Date	Description	
		Page	Summary
0.20	Sep 29, 2005	20	Table 4.6 SFR Information (6) revised - 0145h: POCR0 → TRDPOCR0 - 0146h, 0147h: TRDCNT0 → TRD0 - 0148h, 0149h: GRA0 → TRDGRA0 - 014Ah, 014Bh: GRB0 → TRDGRB0 - 014Ch, 014Dh: GRC0 → TRDGRC0 - 014Eh, 014Fh: GRD0 → TRDGRD0 - 0155h: POCR1 → TRDPOCR1 - 0156h, 0157h: TRDCNT1 → TRD1 - 0158h, 0159h: GRA1 → TRDGRA1 - 015Ah, 015Bh: GRB1 → TRDGRB1 - 015Ch, 015Dh: GRC1 → TRDGRC1 - 015Eh, 015Fh: GRD1 → TRDGRD1
		22	5. Electrical Characteristics added
1.00	Nov 15, 2006	All pages	"Preliminary" and "Under development" deleted
		2	Table 1.1 Functions and Specifications for R8C/20 Group revised. NOTE1 deleted.
		3	Table 1.2 Functions and Specifications for R8C/21 Group revised. NOTE1 deleted.
		5	Table 1.3 Product Information for R8C/20 Group; "R5F2120AJFP (D)", "R5F2120CJFP (D)", "R5F2120AKFP (D)", "R5F2120CKFP (D)", and NOTE added. Figure 1.2 Type Number, Memory Size, and Package of R8C/20 Group; "A: 96 KB" and "C: 128 KB" added.
		6	Table 1.4 Product Information for R8C/21 Group; "R5F2121AJFP (D)", "R5F2121CJFP (D)", "R5F2121AKFP (D)", "R5F2121CKFP (D)", and NOTE added. Figure 1.3 Type Number, Memory Size, and Package of R8C/21 Group; "A: 96 KB" and "C: 128 KB" added.
		13	Figure 3.1 Memory Map of R8C/20 Group revised.
		14	Figure 3.2 Memory Map of R8C/21 Group revised.
		15	Table 4.1 SFR Information (1) ⁽¹⁾ ; NOTE8; "The CSPROINI bit in the OFS register is set to 0." → "The CSPROINI bit in the OFS register is 0." revised.
		21	Table 5.1 Absolute Maximum Ratings; Power dissipation revised. Table 5.2 Recommended Operating Conditions; System clock revised.
		26	Table 5.8 Voltage Monitor 1 Reset Circuit Electrical Characteristics → Table 5.8 Power-on Reset Circuit, Voltage Monitor 1 Reset Circuit Electrical Characteristics ⁽¹⁾ replaced. Table 5.8 revised. NOTE3 added. Table 5.9 Power-on Reset Circuit Electrical Characteristics deleted. Figure 5.3 Power-on Reset Circuit Electrical Characteristics revised.
		27	Table 5.10 High-Speed On-Chip Oscillator Circuit Electrical Characteristics → Table 5.9 High-Speed On-Chip Oscillator Circuit Electrical Characteristics revised.

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Rev.	Date	Description	
		Page	Summary
1.00	Nov 15, 2006	33	Table 5.15 Electrical Characteristics (1) [VCC = 5 V] → Table 5.14 Electrical Characteristics (1) [VCC = 5 V] revised. RAM Hold Voltage, Min.; “1.8” → “2.0” corrected.
		34	Table 5.16 Electrical Characteristics (2) [Vcc = 5 V] → Table 5.15 Electrical Characteristics (2) [Vcc = 5 V] revised. Wait mode revised.
		37	Table 5.21 Electrical Characteristics (3) [VCC = 3 V] → Table 5.20 Electrical Characteristics (3) [VCC = 3 V] revised. RAM hold voltage, Min.; “1.8” → “2.0” corrected.
		38	Table 5.22 Electrical Characteristics (4) [Vcc = 3 V] → Table 5.21 Electrical Characteristics (4) [Vcc = 3 V] revised. Wait mode revised.
2.00	Aug 27, 2008	–	“RENESAS TECHNICAL UPDATE” reflected: TN-16C-A172A/E
		5, 6	Table 1.3, Table 1.4 revised Figure 1.2, Figure 1.3; ROM number “XXX” added
		13, 14	Figure 3.1, Figure 3.2; “Expanding area” deleted
		21	Table 5.2; NOTE2 revised
		23	Table 5.4; NOTE2 and NOTE4 revised
		24	Table 5.5; NOTE2 and NOTE5 revised
		25	Table 5.6; “td(Vdet1-A)” added, NOTE5 added Table 5.7; “td(Vdet2-A)” and NOTE2 revised, NOTE5 added
		26	Table 5.8; “trth” and NOTE2 revised Figure 5.3 revised

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